



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD100N06S4-03	Issued	17. February 2022
MA#	MA005699476		
Package	PG-TO252-3-11	Weight*	374.06 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.184	1.39	1.39	13859	13859
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		576	
	non noble metal	copper	7440-50-8	215.017	57.47	57.55	574822	575571
wire	non noble metal	aluminium	7429-90-5	6.442	1.72	1.72	17222	17222
encapsulation	inorganic material	zinc oxide	1314-13-2	1.201	0.32		3210	
	miscellaneous	miscellaneous	-	6.004	1.61		16052	
	plastics	epoxy resin	-	18.013	4.82		48156	
	inorganic material	silicon dioxide	60676-86-0	94.869	25.36	32.11	253621	321039
lead finish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	9999	9999
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244
solder	non noble metal	tin	7440-31-5	0.080	0.02		215	
	noble metal	silver	7440-22-4	0.100	0.03		268	
	non noble metal	lead	7439-92-1	3.833	1.02	1.07	10248	10731
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.13	5.14	51269	51335
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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